

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
 Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Feb 22, 2014 03:47 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
MOC3052TVM	MOC3052TVM	DIPW-6			INTERNAL PENANG	0.537379	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide. The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties. Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.		
RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
Exemption List Version EL-2011/534/EU None		

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DIPW-6

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	4.043	Supplier		Gallium Arsenide	0.283	1303-00-0	527
			Supplier		Silicon	3.760	7440-21-3	6997
Coupling Gel	Other Organic Materials	1.830	Supplier		Dimethyl Cyclosiloxanes	0.635	69430-24-6	1182
			Supplier		Methyltrimethoxysilane	0.888	1185-55-3	1652
			Supplier		Xylene	0.307	1330-20-7	571
Die Attach	Other Organic Materials	1.665	Supplier		Acrylic Resin	0.415	54208-63-8	772
			Supplier		Silver	1.250	7440-22-4	2326
Encapsulation	Thermoplastics	414.670	B	Antimony/Antimony Compounds	Antimony Trioxide	12.400	1309-64-4	23075
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	16.600	6386-73-8	30891
			Supplier		Epoxy Resin	95.400	29690-82-2	177528
			Supplier		Silica, vitreous	290.270	60676-86-0	540158
Lead Frame	Copper & its alloys	108.322	Supplier		Copper	105.000	7440-50-8	195393
			Supplier		Iron	2.480	7439-89-6	4615
			Supplier		Phosphorus	0.032	7723-14-0	60
			Supplier		Silver	0.680	7440-22-4	1265
			Supplier		Zinc	0.130	7440-66-6	242
Plating	Other Nonferrous metals & alloys	6.700	Supplier		Tin	6.700	7440-31-5	12468
Wire Bond	Precious metals	0.149	Supplier		Gold	0.149	7440-57-5	277